


AMKOR/ANAM CONFIDENTIAL

Amkor Technology, Inc.  
 Amkor Semiconductor, Inc.  
 Amkor Electronics Philippines, Inc.  
 Manila, Philippines



PACKAGE OUTLINE MATRIX - PAD TOP,  
 5 X 6 BODY, 100/0/1.0  
 1.00 mm THICK (OPTIONAL, ePAD)

PRINTING IS SCALED TO FIT  
 DO NOT SCALE DRAWING

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ALL DIMENSIONS IN MILLIMETERS

Symbol	MIN.	NOM.	MAX.	REF.
A	0.05	~	1.50	13
A1	0.05	~	0.15	
A2	0.25	~	1.00	1
B	0.20	~	0.80	4
B1	0.20	~	0.80	4
B2	0.20	~	0.80	4
C	0.20	~	0.80	4
D	0.20	~	0.80	4
E	0.20	~	0.80	4
F	0.20	~	0.80	4
G	0.20	~	0.80	4
H	0.20	~	0.80	4
I	0.20	~	0.80	4
J	0.20	~	0.80	4
K	0.20	~	0.80	4
L	0.20	~	0.80	4
M	0.20	~	0.80	4
N	0.20	~	0.80	4
O	0.20	~	0.80	4
P	0.20	~	0.80	4
Q	0.20	~	0.80	4
R	0.20	~	0.80	4
S	0.20	~	0.80	4
T	0.20	~	0.80	4
U	0.20	~	0.80	4
V	0.20	~	0.80	4
W	0.20	~	0.80	4
X	0.20	~	0.80	4
Y	0.20	~	0.80	4
Z	0.20	~	0.80	4
CC1	0.08	~	0.08	9
CC2	0.08	~	0.08	9
CC3	0.08	~	0.08	9

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X	0.20	~	0.80	4
Y	0.20	~	0.80	4
Z	0.20	~	0.80	4
CC1	0.08	~	0.08	9
CC2	0.08	~	0.08	9
CC3	0.08	~	0.08	9

- NOTES:
- ALL DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5M-1994.
  - WITH LEAD 2.5X THE LEAD OF THE SEATING LINE AND CONDUCTIVE LEAD.
  - LEADS WHERE LEADS EXIT PLASTIC BODY AT MAIN PLANE H, VISEN TO BE DETERMINED AT SEATING PLANE C.
  - LEADS WHERE LEADS EXIT PLASTIC BODY AT MAIN PLANE H, VISEN TO BE DETERMINED AT SEATING PLANE C.
  - ALLOWABLE HOLE PROTRUSION IS 0.054 MM IN DI AND EI.
  - THESE DIMENSIONS TO BE DETERMINED AT MAIN PLANE H.
  - PACKAGE TOP DIMENSIONS ARE SMALLER THAN BOTTOM DIMENSIONS AND TOP OF PACKAGE WILL NOT OVERSHOULDER BOTTOM OF PACKAGE.
  - ALLOWABLE DIMENSION PROTRUSION SHALL BE 0.054 MM TOTAL CONDITION. DIMENSIONS CANNOT BE LOCATED ON THE LOWER PORTION OF THE FOOT.
  - MINIMUM ALLOWABLE DIE THICKNESS TO BE ASSEMBLED IN THIS PACKAGE SHALL BE 0.20 MILLIMETERS. SPEC PUBLICATION 95 REGISTRATION NUMBER, VARIATION 444 AND 445.
  - A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE CENTER OF THE DIE.
  - THESE DIMENSIONS ARE SPECIFIED ON THE EXPOSED PAD DIMENSIONS AND REPRESENT THE SIZE OF THE BONDING DIAPHRAGM.
  - EXPOSED PAD SHALL BE CRYSTALLINE WITH BOTTOM OF PACKAGE WITHIN 0.05.
  - CORNER CHAMFER OF EXPOSED DIE PAD SHALL BE WITHIN 0.20 MM.